



Material Content Data Sheet



Sales Product Name		TLE7183F		Issued		25. September 2017		
MA#		MA000792844						
Package		PG-VQFN-48-14		Weight*		214.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.778	3.62	3.62	36217	36217
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		148	
	non noble metal	zinc	7440-66-6	0.127	0.06		591	
	non noble metal	iron	7439-89-6	2.537	1.18		11812	
wire	non noble metal	copper	7440-50-8	103.000	47.96	49.21	479599	492150
	noble metal	gold	7440-57-5	2.663	1.24	1.24	12400	12400
	encapsulation	organic material	carbon black	1333-86-4	0.457	0.21		2128
encapsulation	plastics	epoxy resin	-	14.167	6.60		65965	
	inorganic material	silicondioxide	60676-86-0	76.775	35.75	42.56	357489	425582
leadfinish	non noble metal	tin	7440-31-5	4.336	2.02	2.02	20191	20191
plating	noble metal	silver	7440-22-4	0.663	0.31	0.31	3086	3086
glue	plastics	epoxy resin	-	0.356	0.17		1660	
	noble metal	silver	7440-22-4	1.871	0.87	1.04	8714	10374
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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